PCN Number:	20130507001	**PCN Date:**	05/09/2013
Title:	Qualification of JCAP as Alternate Assembly and test Site for selected products in DSBGA package		

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	08/09/2013	**Estimated Sample Availability:**	05/09/2013

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☒	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

Qualification of JCAP as an alternate backend assembly and test site.

	TI Melaka-AT	**JCAP-AT**
Solder Ball:	SnAgCu	**SnAgCu**

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
TIEM-AT	Assembly Site Origin (22L)	ASO: CU6
JCAP-AT	Assembly Site Origin (22L)	ASO: JCP

Sample product shipping label to show code location only - not actual product label

Product Affected:

LM10524TME/NOPB	LM3630TME/NOPB	LM3642TLX-LT/NOPB	LP5907UVX-2.8/NOPB
LM10524TMX/NOPB	LM3630TMX/NOPB	LM3642TLX/NOPB	LP5907UVX-3.1/NOPB
LM3630ATME	LM3642TLE-LT/NOPB	LP5907UVX-1.2/NOPB	LP5907UVX-4.5/NOPB
LM3630ATMX	LM3642TLE/NOPB	LP5907UVX-1.8/NOPB	

Qualification Plan

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle: LM3564A1TME/NOPB (MSL1-260C)

Qualification Schedule:	**Start:**	April 2013	**End:**	July 2013

Package Construction Details

Assembly & Bump Site:	JCAP	**Bump Composition:**	SnAgCu
# Pins-Designator, Family:	20-YFQ, DSBGA	**Bump Diameter:**	0.25mm

Qualification: ☒ **Plan** ☐ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
High Temp. Operating Life	125C (1000hrs)	77/0	77/0	77/0
Electrical Characterization	Per Datasheet specifications	30/0	--	--
High Temp. Storage Bake	150C (1000 Hrs)	77/0	--	--
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (700 Cyc)	77/0	77/0	77/0
ESD CDM	+/- 250	3/0	3/0	3/0
ESD HBM	+/- 1000V	3/0	3/0	3/0
Latch-up (25C, 70C, 125C)	> 2 x Vddnom and >2 x Iddnom @ max Tj	6/0	6/0	6/0

Notes: **Tests require preconditioning sequence: MSL1-260C

Qualification Results

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Schedule:	**Start:**	January 2012	**End:**	April 2012

Qualification Device: LP5907UVE (MSL 1-260C)

Package Construction Details

Assembly & Bump Site:	JCAP	**Bump Composition:**	SnAgCu
# Pins-Designator, Family:	4 - YKE, DSBGA	**Bump Diameter:**	0.20mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot 3
High Temp. Operating Life	125C (1000hrs)	77/0	--	--
**Autoclave 121C	121C, 1 atm (96 Hrs)	77/0	80/0	80/0
**THBT	85C/85%	77/0	77/0	78/0
**T/C -40C/125C	-40C/+125C (1000 Cyc)	76/0	80/0	80/0
ESDH	2000V, 1.5K Ohm, 100pF	3/0	--	--
ESDM	200V, 0 Ohm, 200pF	3/0	--	--
Latch-up	I & OV test @ Max Op. Temp	6/0	--	--

Notes: **Tests require preconditioning sequence: MSL1-260C

Qualification Results

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Qualification Schedule:	**Start:** January 2012	**End:**	April 2012

Qualification Device: BP64UKE (MSL 1-260C)			
Package Construction Details			
Assembly & Bump Site:	JCAP	**Bump Composition:**	SnAgCu
# Pins-Designator, Family:	4 - YKE, DSBGA	**Bump Diameter:**	0.20mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail
Board Level Drop	--	pass
Board Level TMCL	--	pass

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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